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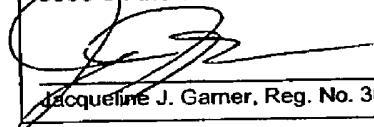
Applicant: Tsuga et al.
Serial No.: 10/085,725
Filing Date: 02/28/2002
Customer No.: 23494

Art Unit: 1746
Examiner: Kornakov, M.
Docket No.: TI-31621
Conf. No.: 1672

Title: METHOD AND DEVICE FOR REMOVING PARTICLES ON
SEMICONDUCTOR WAFERS

CERTIFICATION OF FACSIMILE TRANSMISSION

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NAME OF INVENTOR(S):	
Tsuga et al	
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